TOSHIBA Photocoupler GaAłAs IRed & Photo-IC

TLP113

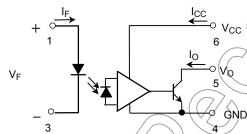
Isolated Line Receiver Simplex / Multiplex Data Transmission Computer-Peripheral Interface Microprocessor System Interface Digital Isolation For A / D, D / A Conversion

The TOSHIBA mini flat coupler TLP113 is a small outline coupler, suitable for surface mount assembly.

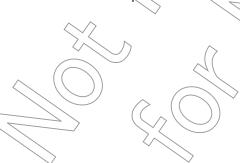
TLP113 consists of a GaAℓAs light emitting diode, optically coupled to an integrated high gain, high speed photodetector whose output is an open collector, schottky clamped transistor.

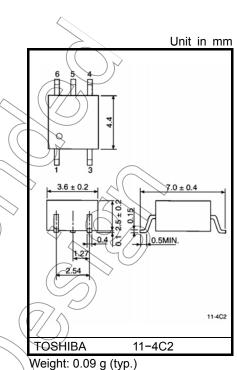
- Input current thresholds: IF=10mA(max.)
- Switching speed: 10MBd(typ.)
- TTL / LSTTL compatible: VCC=5V
- Guaranteed performance over temp.: 0~70°C
- Isolation voltage: 2500Vrms(min.)
- UL recognized: UL1577 file no. E67349

Schematic

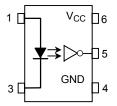


(Note) A 0.1µF bypass capacitor must be connected between pins 4 and 6.





Pin Configuration(top view)



- 1 : Anode
- 3 : Cathode
- 4 : GND 5 : Output
- (Open collector)
- 6 : V_{CC}

TRUTH TABLE (Positive Logic)

INPUT	OUTPUT
н	L
L	Н

Absolute Maximum Ratings (Ta = 25°C)

	Characteristic		Symbol	Rating	Unit	
	Forward current		١ _F	20	mA	
	Pulse forward current	(Note 1)	I _{FP}	40	mA	
LED	Peak transient forward current	(Note 2)	I _{FPT}	1	A	
	Reverse voltage		VR	5	v	
	Output current		Ι _Ο	25	mA \\\	>
Detector	Output voltage		VO	7	(N)	
	Supply voltage (1 minute maximum)		V _{CC}	7		
	Output power dissipation		PO	40 ((m₩	
Oper	ating temperature range		T _{opr}	-40~85	C	
Stora	ge temperature range		T _{stg}	-55~125	> °C	$(\)$
Lead	solder temperature (10s)		T _{sol}	260	°C	
	ion voltage 1 min., RH ≤ 60%,	Note 4)	BVS	2500	Vrms	$\tilde{\bigcirc}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1) 50% duty cycle, 1ms pulse width.

(Note 2) Pulse width≤1µs, 300pps.

Recommended Operating Conditions

Characteristic	Symbol	Min.	Тур	Max.	Unit
Input voltage, low level	V _{FL}	3		1.0	V
Input current, high level	IFH C	13*	16	20	mA
Supply voltage**	V _{CC}	4.5	5	5.5	V
Fan out (TTL load, each channel)	N	\nearrow I		8	_
Operating temperature	Topr	0		70	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device: Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

* 13mA is a guard banded value which allows for at least 20% CTR degradation.

Initial input current threshold value is 10mA or less.

**This item denotes operating ranges, not meaning of recommended operating conditions.

Electrical Characteristics(unless otherwise specified, Ta=0~70°C, V_{CC}=4.5~5.5V, V_{FL} \leq 1.0V)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Forward voltage	VF	I _F =10mA, Ta=25°C	—	1.65	1.80	V
Forward voltage temperature coefficient	V _F / Ta	I _F =10mA		-2	_	mV / °C
Reverse current	I _R	V _R =5V, Ta=25°C	$-\hat{c}$	$\overline{}$	10	μA
Capacitance between terminals	CT	V _F =0, f=1MHz, Ta=25°C	<u> </u>	45	_	pF
High level output current	la	V _F =1.0, V _O =5.5V	$\langle \bigcirc \rangle$	—	250	A
	I _{ОН}	V _F =1.0, V _O =5.5V, Ta=25°C	-/	0.5	10	μA
Low level output voltage	V _{OL}	I _F =10mA I _{OL} =13mA(sinking)	9_	0.4	0.6	V
"H level output→ L level output" input current	IFH	I _{OL} =13mA(sinking) V _{OL} =0.6V	_	2	10	mA
High level supply current	ICCH	V _{CC} =5.5V, I _F =0	$\langle - \rangle$	$\Box $	15	mA
Low level supply current	ICCL	V _{CC} =5.5V, I _F =16mA		12	18	mA
Input-output insulation leakage current	IS	V _S =3540V, t=5s Ta=25°C (Note 4)	$(\bigcirc$) -	100	μA
Isolation resistance	R _S	R.H. ≤ 60%, VS=500V DC [ra=25°C (Note 4)	5×10 ¹⁰	10 ¹⁴	_	Ω
Stray capacitance between input to output	CS	V _S =0, f=1MHz Ta=25°C (Note 4)	_	0.8	_	pF

* All typical values are V_{CC}=5V, Ta=25°C

Switching Characteristics (V_{CC}=5V, Ta=25°C)

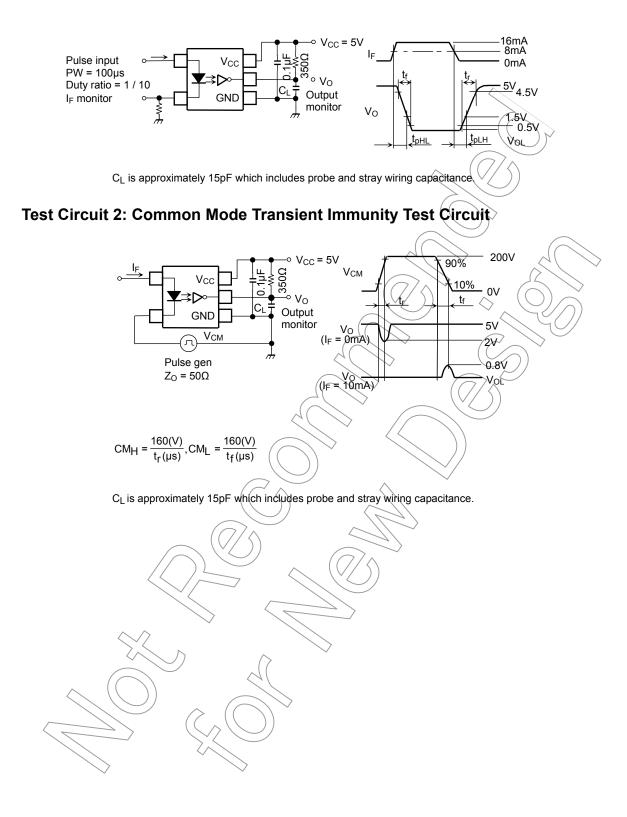
Characteristic	Symbol	Test Cir– cuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay time (H→L)	t _p HL	1	I _F =0→16mA C _L =15pF, R _L =350Ω	- 4	60	120	ns
Propagation delay time (L→H)	t _p LH	1	I _F =16→0mA C _L =15pF, R _L =350Ω		60	120	ns
Output rise-fall time (10–90%)	t _r , t _f	2	R _L =350Ω, C _L =15pF I _F =0 → 16mA	$\overline{\mathcal{O}}$	30	_	ns
Common mode transient imunity at high output level	CM _H	2	I _F =0mA, V _{CM} =200V _{p-p} V _{O(min)} =2V, R _L =350Ω		200		V / μs
Common mode transient imunity at low output level	CML	2	$I_{F}=16mA, V_{CM}=200V_{p-p}$ $V_{O(max)}=0.8V,$ $R_{L}=350\Omega$	_	-500		V / μs

(Note 4) Device considered a two-terminal device: Pins 1 and 3 shorted together, and pins 4, 5 and 6 shorted together.

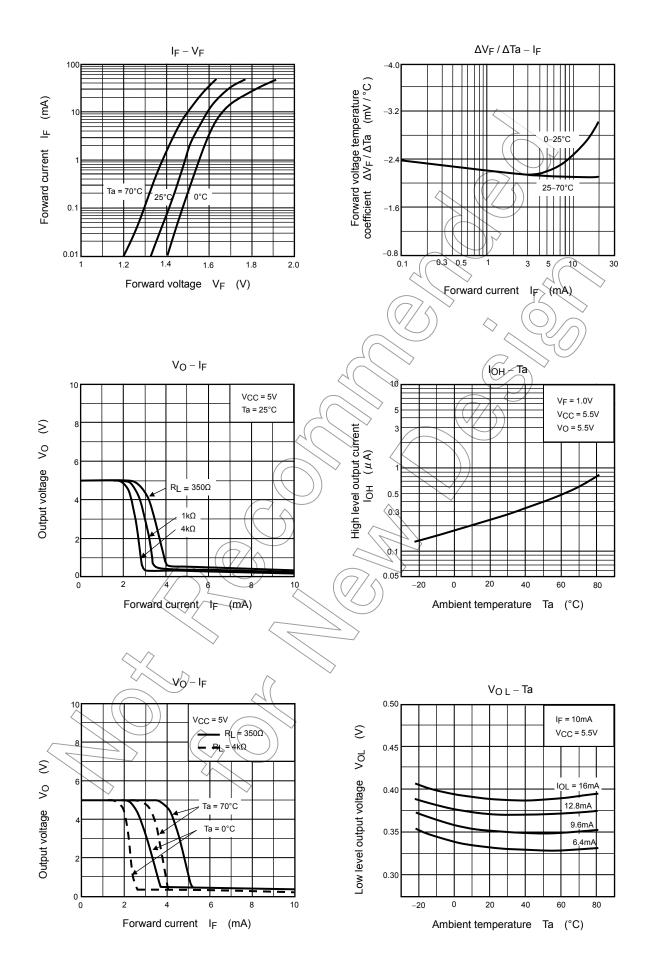
(Note 5) The V_{CC} supply voltage to each TLP113 isolator must be bypassed by 0.1µF capacitor, this can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to package V_{CC} and GND pins of each device.

(Note 6) Maximum electrostatic discharge voltage for any pins: 180V(C=200pF, R=0)

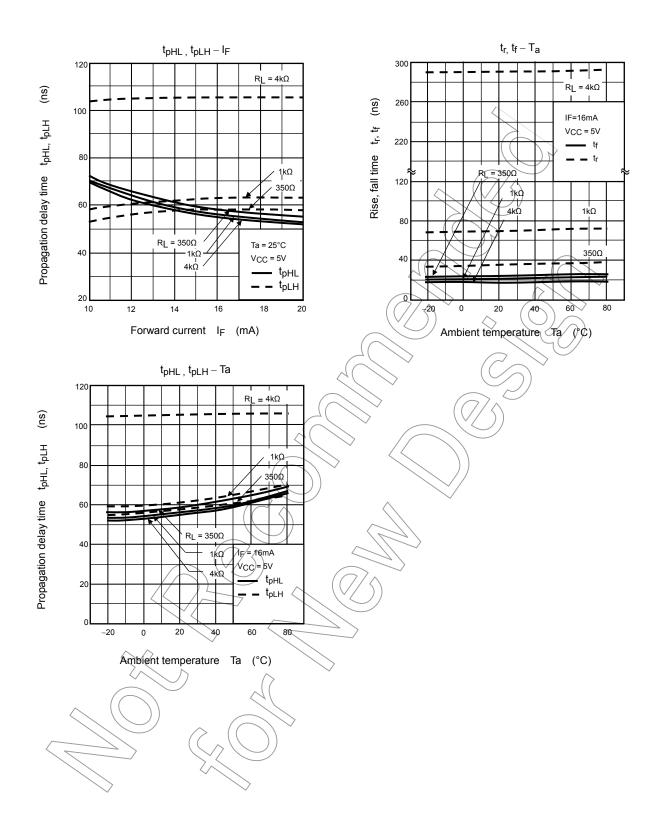
Test Circuit 1: Switching Time Test Circuit



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